TECHNICAL DATA DATASHEET 5500, Rev. B

10KVOLT, 9 AMP DIODE MODULE

Features

- 10 Sections of 1kV/3A/75ns Glass Hermetic Diodes
- Isolated Ceramic Case for Heat Transfer
- Interlocking Features for Stacking Modules
- Threaded Mounting Holes
- Threaded Terminals for Anode and Cathode
- Add suffix "HV" for screening per Sensitron HV Stack Screening Flow, HV-200 (SHVD0910BHV)



ELECTRICAL CHARACTERISTICS

(T_J=25°C UNLESS OTHERWISE SPECIFIED)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT				
DIODE MODULE SPECIFICATIONS									
V _f	Forward Voltage $I_f = 6A$, $T_A=25$ °C $I_f = 6A$, $T_A=100$ °C	-	-	16 14	V				
I _R	Reverse Current V _R =10000V, T _A =25°C V _R =10000V, T _A =100°C	-	-	20 300	μΑ				
BV _R	Breakdown Voltage I _R =500µA, T _A =25°C I _R =500µA, T _A =100°C	10 10	-	-	kV				
t _{rr}	Reverse Recovery Time $I_f = 0.5A$, $I_R = 1A$, $I_{rr} = 0.25A$, $T_A = 25$ °C $I_f = 0.5A$, $I_R = 1A$, $I_{rr} = 0.25A$, $T_A = 100$ °C	-	-	100 250	ns				
CJ	Junction Capacitance V_R =10V, f = 1MHz, V_{AC} = 50mV Each section has 47pF, 2KV ceramic capacitor across the three diodes in parallel (for AC balancing)	-	30	50	pF				
I _S	Surge Current t = 8.3mS, Half Sine, T _A =25°C	240	-	-	А				

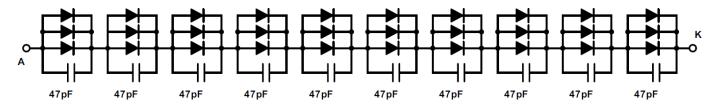
Note: Production units are tested at room temperature. Low/High temperature operation is guaranteed by design.

THERMAL AND MECHANICAL CHARACTERISTICS

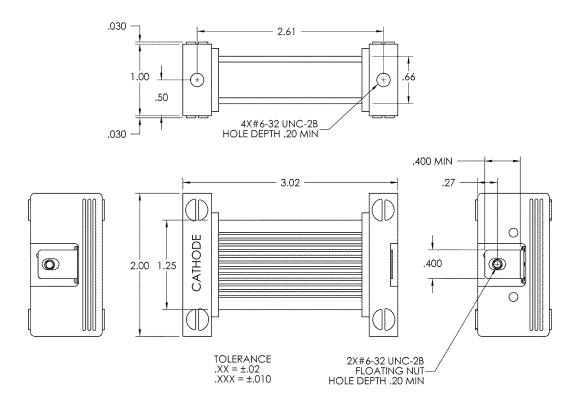
THERMIAE AND MECHANICAE CHARACTERISTICS								
SYMBO	DL PARAMETER	MIN	TYP	MAX	UNIT			
$R_{\theta JC}$	Diode Junction-to-Case Thermal Resistance (each section)	-	-	7	°C/W			
V _{iso}	Isolation to Case	-	-	15	kV DC			
TJ	Operating Junction Temperature	-55	-	150	°C			
T _{STG}	Storage Temperature	-55	-	150	°C			
	Torque Mounting Holes: #6-32 UNC-2B Brass Thread Terminal Holes: #6-32 SS Nut		6 8	8 10	in-lb			
	Weight Module	-	125	200	g			

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Schematic Diagram:



Mechanical Outline (inches):



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